

REMARKS

Claims 2, 3, 5, 8 and 19-21 are pending in this application. By this Second Amendment After Final Rejection, claims 2, 3, 5 and 8 are amended; claims 19-21 are added; and claims 7 and 18 are canceled. No new matter is added. In view of the foregoing amendments and the following remarks, reconsideration and allowance are respectfully requested.

Applicant gratefully acknowledges the Office Action's indication that the March 19 Amendment After Final Rejection is entered.

Entry of the amendments is proper under 37 C.F.R. §1.116 since the amendments: (a) place the application in condition for allowance for the reasons discussed herein; (b) do not raise any new issue requiring further search and/or consideration since the amendments amplify issues previously discussed throughout prosecution; (c) do not present any additional claims without canceling a corresponding number of finally rejected claims; and (d) place the application in better form for appeal, should an appeal be necessary. Entry of the amendments is thus respectfully requested.

I. Rejection Under 35 U.S.C. §102(b)

The Office Action rejects claims 2, 3, 5, 7, 8 and 18 under 35 U.S.C. §102(b) as being anticipated by Tsukahara, U.S. Patent No. 6,051,093. The rejection is respectfully traversed.

Tsukahara fails to disclose "the bumps are pushed into the base substrate from the first surface through the base substrate to a second surface opposite to the first surface, and then electrically connecting the bumps to interconnecting lines formed on the second surface of the base substrate; and mounting a second semiconductor chip on the second surface of the base substrate," as recited in claim 19. Claim 19 replaces claim 18.

Tsukahara, on the other hand, discloses that the protruding bump 3 of the semiconductor element 1 contacts the conductive paste 7 in the hole of the circuit board 4 (col. 6, lines 20-22). The bumps in Tsukahara contact the conductive paste 7 at the mounting

side of the base substrate. The bumps in Tsukahara cannot contact the opposing side of the base substrate because the circuit board 4 is surrounded by a copper foil 5 at the mounting side (Fig. 1). Furthermore, Tsukahara does not disclose or suggest mounting of a second semiconductor as claimed.

Accordingly, Tsukahara fails to disclose mounting a first semiconductor chip on a first surface of a base substrate and mounting a second semiconductor chip on the second surface of the base substrate, as recited in claim 19.

Because Tsukahara does not literally disclose the claimed invention, it cannot provide the basis for rejection under 35 U.S.C. §102. Further, Tsukahara does not suggest such a structure. Thus, it is respectfully requested that the rejection be withdrawn.

For at least these reasons, Applicant respectfully submits that Tsukahara fails to disclose or even suggest, the features recited in independent claim 19. Claims 2, 3, 5, 8, 20 and 21, which depend from independent claim 19, are likewise distinguished over the applied art for at least the reasons discussed, as well as for the additional features they recite. Reconsideration and withdrawal of the rejection are respectfully requested.

II. Double Patenting

The Office Action discloses that "the instant claims are not subject to double patenting, but may be subject to provisional double patenting depending on the final form of the claims." Accordingly, it is applicant's belief that no response is required at this time.

III. Conclusion

In view of the foregoing amendments and remarks, Applicant respectfully submits that this application is in condition for allowance. Favorable consideration and prompt allowance of claims 2, 3, 5, 8 and 19-21 are earnestly solicited.

Should the Examiner believe that anything further would be desirable in order to place this application in better condition for allowance, the Examiner is invited to contact Applicant's undersigned representative at the telephone number listed below.

Respectfully submitted,



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